

QT-Brightek Chip LED Series

SMD 0606 RGB LED

Part No.: QBLP600-RGB

Product: QBLP600-RGB	Date: April 26, 2016	Page 1 of 10
	Version# 2.1	

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Introduction

Feature:

- Water clear lens
- Package in tape and reel
- Ultra bright 0606 LED package
- Common Anode
- InGaN technology for IB/IG
- AlInGaP technology for R

Description:

These ultra bright 0606 RGB LEDs have a height profile of 0.80mm. Combination of high brightness output and small footprint, these LEDs are ideal for keypad backlighting, status indication, and color mixing applications.

Application:

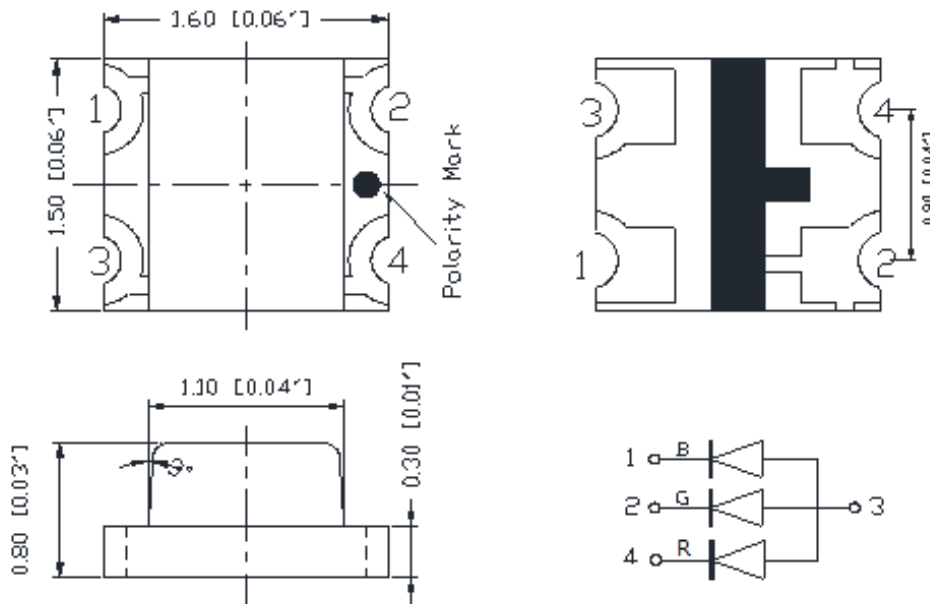
- Status indication
- Back lighting application

Certification & Compliance:

- TS16949
- ISO9001
- RoHS Compliant



Dimension:



Units: mm / tolerance = +/-0.1mm

Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	I _F (mA)	V _F (V)		λ _D (nm)			I _V (mcd)	
			Typ.	Max	Min	Typ.	Max	Min	Typ.
QBLP600-RGB	Red	20	2.0	2.5	615	620	630	80	125
	True Green	20	3.4	3.7	515	520	525	200	380
	Blue	20	3.1	3.7	465	470	475	40	75

Absolute Maximum Rating

Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SO L} (°C)**
InGaN (IB/IG)	111	30	125	5	-40 ~ + 80	-40 ~ +85	260
AllnGaP (R)	75	30	125	5	-40 ~ + 80	-40 ~ +85	260

*Duty 1/8 @ 1KHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F for AllnGaP @ I_F=20mA

Bin	Min.	Max.	Unit
□	1.7	2.5	V

Forward Voltage V_F for InGaN @ I_F=20mA

Bin	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

Luminous Intensity I_V @ $I_F=20mA$

Bin	Min.	Max.	Unit
F	40	50	mcd
G	50	63	
H	63	80	
I	80	100	
J	100	125	
K	125	160	
L	160	200	
M	200	250	
N	250	320	
O	320	400	
P	400	500	
Q	500	630	

Dominant Wavelength λ_D for Red @ $I_F=20mA$

Bin	Min.	Max.	Unit
s	615	620	nm
t	620	625	
u	625	630	

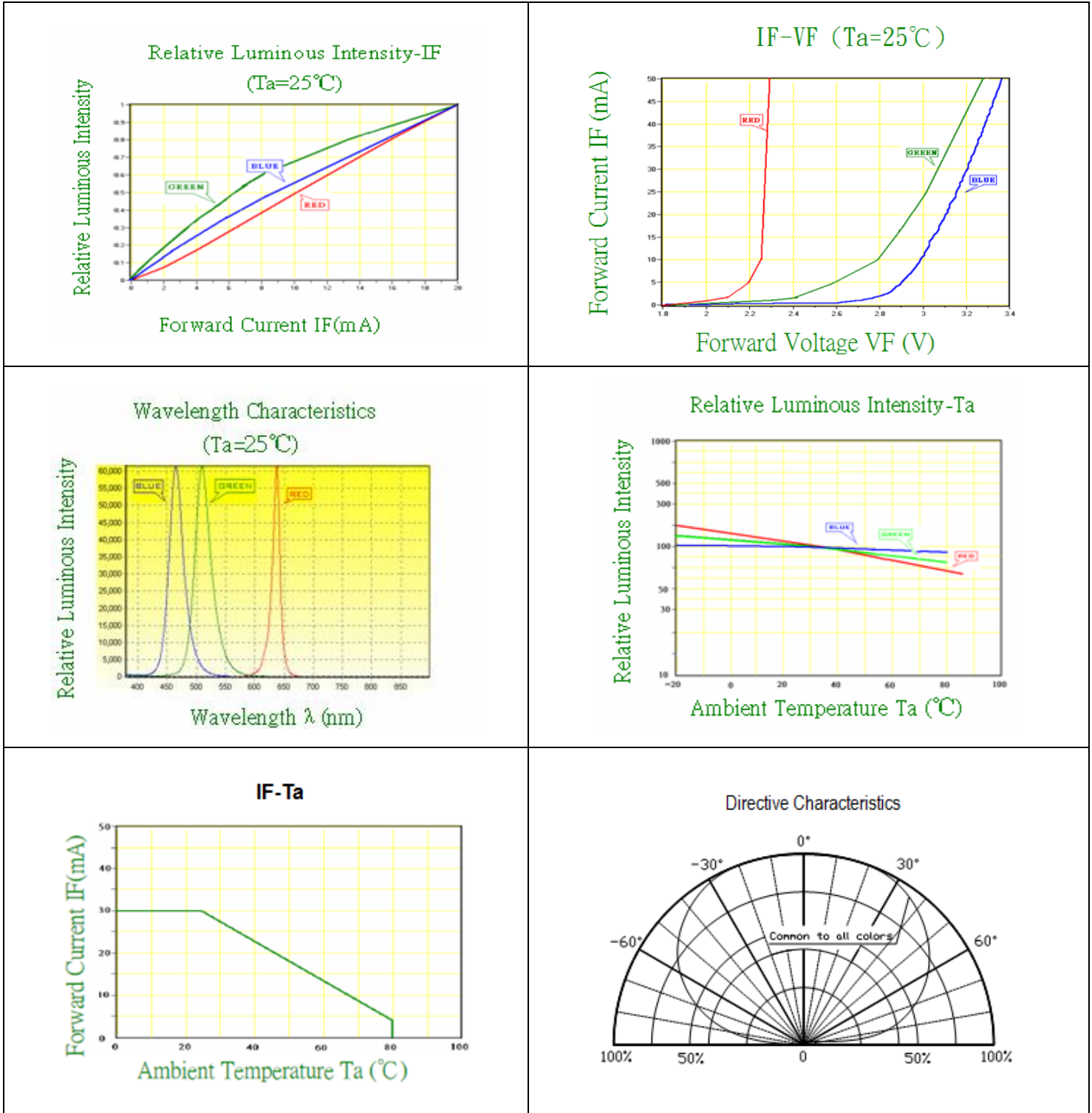
Dominant Wavelength λ_D for Green @ $I_F=20mA$

Bin	Min.	Max.	Unit
S	515	517.5	nm
T	517.5	520	
U	520	522.5	
V	522.5	525	

Dominant Wavelength λ_D for Blue @ $I_F=20mA$

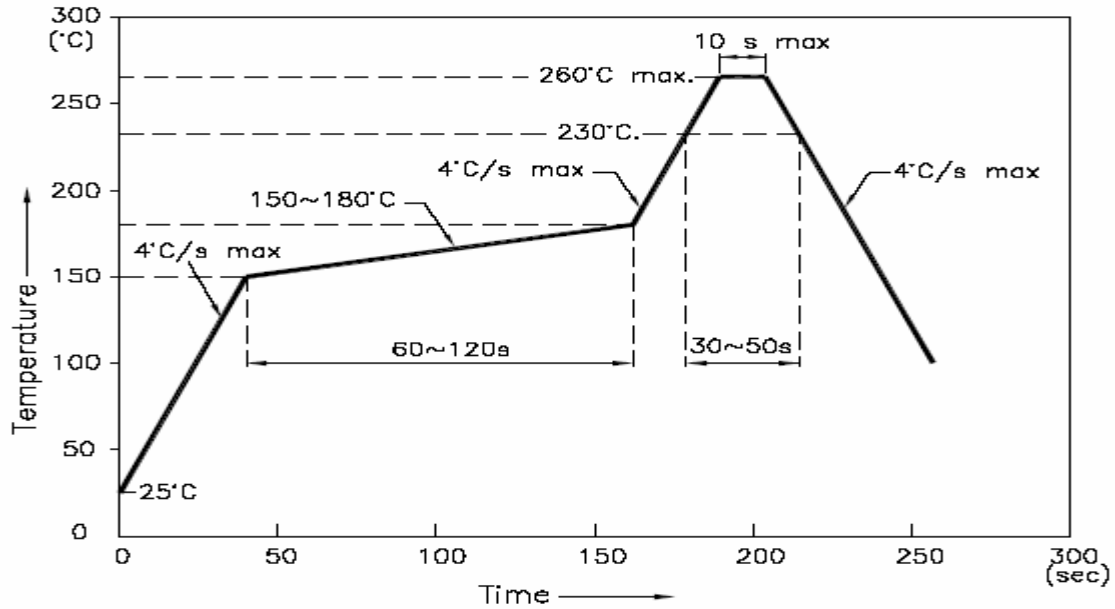
Bin	Min.	Max.	Unit
G	465	467.5	nm
H	467.5	470	
I	470	472.5	
J	472.5	475	

Characteristic Curves

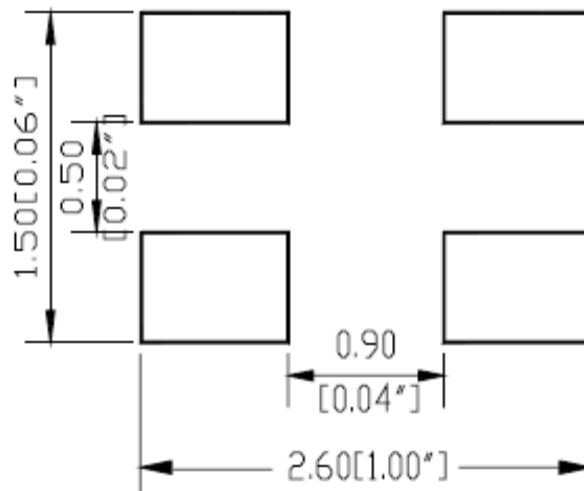


Solder Profile & Footprint

- Recommended tin solder specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



Recommended Pad Layout

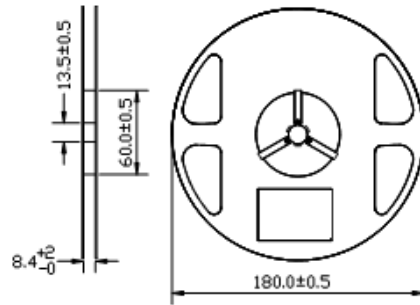


Units: mm

Tolerance: ± 0.1mm

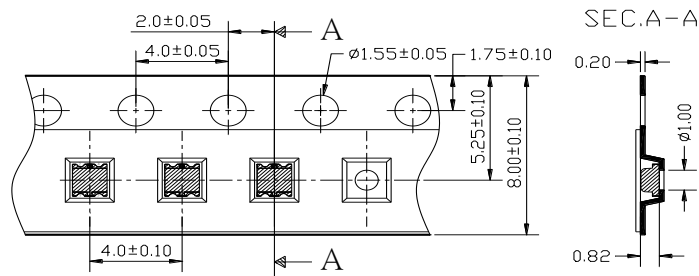
Packing

Reel Dimension:



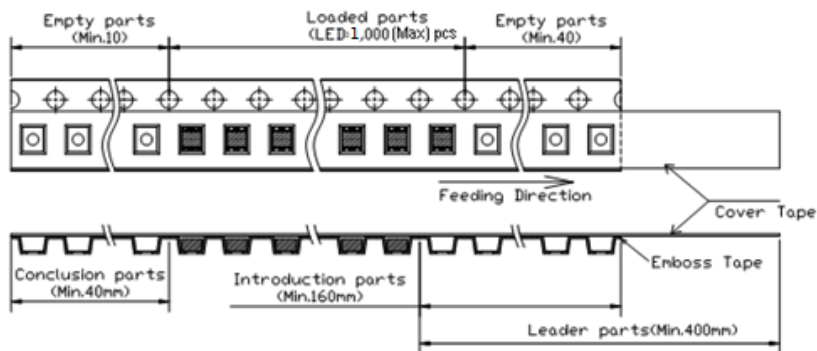
Unit: mm

Tape Dimension:

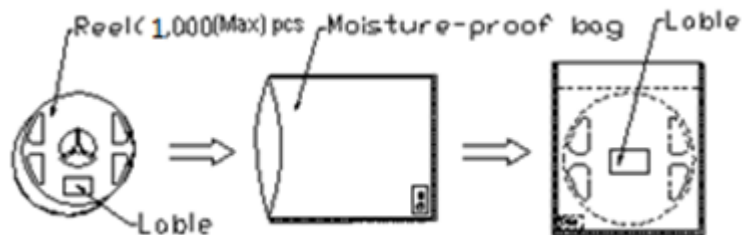


Unit: mm

Arrangement of Tape:



Packaging Specification:



Labeling



Part No: _____

Customer P/N: _____

Item: _____

Q'ty: _____

Vf: _____

Iv: _____

WI: _____

Date: _____

Made in China

Ordering Information

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP600-RGB	QBLP600-RGB	Red: I _v =125mcd typ. @ I _F =20mA, λ _D =615nm to 630nm	1,000 units
		True Green: I _v =380mcd typ. @ I _F =20mA, λ _D =515nm to 525nm	
		Blue: I _v =75mcd typ. @ I _F =20mA, λ _D =465nm to 475nm	

Revision History

Description:	Revision #	Revision Date
New Release of QBLP600-RGB	V1.0	02/03/2011
Brightness Updates	V1.1	06/01/2011
Labeling update	V1.2	06/25/2011
Spec Update	V1.3	12/12/2011
Update format	V2.0	07/15/2013
Update packing spec and PCB drawing	V2.1	04/26/2016

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.